

A CUSTOMIZED POLISHING PAD FOR SELECTIVE PROCESS  
PERFORMANCE DURING CHEMICAL MECHANICAL POLISHING

ABSTRACT OF THE DISCLOSURE

5           The present invention comprises a customized polishing pad for use  
in a wafer polishing machine. The polishing pad of the present invention  
includes a polishing surface integral with the polishing pad. The polishing  
surface is adapted to frictionally contact a wafer in the polishing machine,  
thereby polishing the wafer. The polishing surface of the polishing pad  
10 includes at least two areas, where each area is adapted to frictionally  
contact the wafer and achieve a polishing effect specific for that area. A  
customized polishing effect is achieved by the polishing pad of the present  
invention when the wafer is selectively moved frictionally against the at  
least two areas by the wafer polishing machine.

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